L Number	Hits	Search Text	DB	Time stamp
1	2	5969461.pn.	USPAT;	2004/09/14
		_	US-PGPUB;	13:28
			EPO; JPO;	
			DERWENT; IBM TDB	
2	2	6078229.pn.	USPAT;	2004/09/14
		•	US-PGPUB;	13:28
			EPO; JPO;	
			DERWENT; IBM TDB	
3	2	6262513.pn.	USPAT;	2004/09/14
		_	US-PGPUB;	13:30
			EPO; JPO;	
			DERWENT; IBM TDB	
4	1		USPAT	2004/09/14
				13:29
5	1		USPAT	2004/09/14
6	1		USPAT	13:29   2004/09/14
	*			13:30
7	1		USPAT	2004/09/14
		6310431	MCDAM.	13:30
8	2	6310421.pn.	USPAT; US-PGPUB;	2004/09/14
			EPO; JPO;	13.31
			DERWENT;	
9	2	6402104 mm	IBM_TDB	2004/00/14
9	4	6492194.pn.	USPAT; US-PGPUB;	2004/09/14
			EPO; JPO;	
			DERWENT;	
10	650254	(al ceramic silicon polymer glass	IBM_TDB USPAT;	2004/09/14
10	030234	transparent) with (substrate carrier)	US-PGPUB;	13:33
			EPO; JPO;	
			DERWENT;	
11	134684	(surface with (acoustic acoustical	IBM_TDB USPAT;	2004/09/14
		acoustically wave))	US-PGPUB;	13:34
			EPO; JPO;	
			DERWENT;	
12	2677087	ccd semiconductor chip die (integrated	IBM_TDB USPAT;	2004/09/14
		adj circuit) ic dice	US-PGPUB;	13:35
			EPO; JPO;	
			DERWENT; IBM TDB	
13	10118	(ccd semiconductor chip die (integrated	USPAT;	2004/09/14
		adj circuit) ic dice) same ((surface with	US-PGPUB;	13:35
		(acoustic acoustical acoustically wave)))	EPO; JPO;	
			DERWENT; IBM TDB	
14	2853	((al ceramic silicon polymer glass	USPAT;	2004/09/14
		transparent) with (substrate carrier))	US-PGPUB;	13:36
		and ((ccd semiconductor chip die (integrated adj circuit) ic dice) same	EPO; JPO;	
		((surface with (acoustic acoustical	DERWENT; IBM_TDB	
		acoustically wave))))		
15	740	((al ceramic silicon polymer glass	USPAT;	2004/09/14
		transparent) with (substrate carrier)) same ((ccd semiconductor chip die	US-PGPUB; EPO; JPO;	13:36
		(integrated adj circuit) ic dice) same	DERWENT;	]
		((surface with (acoustic acoustical	IBM_TDB	
L	l	acoustically wave))))	L	

16	170414	(edge end outer corner border) with (buffer buffering buffered polymer organic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14
17	2	<pre>(((al ceramic silicon polymer glass transparent) with (substrate carrier)) same ((ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave))))) same ( (edge end outer corner border) with (buffer buffering buffered polymer organic))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:39
18	176		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:42
19	701717	bump ball bga fhipchip (flip adj3 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:42
20	701778	bump ball bga flipchip (flip adj3 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:43
21	81428	(ccd semiconductor chip die (integrated adj circuit) ic dice) same (bump ball bga flipchip (flip adj3 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:44
22	13120	<pre>((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:45
23	539	<pre>(((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))) and ((surface with (acoustic acoustical acoustically wave)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/14 13:45
24	53	<pre>((((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))) and ((surface with (acoustic acoustical acoustically wave)))) and ( (edge end outer corner border) with (buffer buffering buffered polymer organic))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:45